

	Typ	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	24010	bond\$4 near8 (solder or (epoxy near4 conductive))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/09 15:20
2	BRS	L2	4520	1 and wafer	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/09 15:20
3	BRS	L3	3432	2 and (pad or pads)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/09 15:20
4	BRS	L4	7547	1 same (pad or pads)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/09 15:20
5	BRS	L5	4428	4 same (connect\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/09 15:22

	Typ	L #	Hits	Search Text	DBs	Tim Stamp
6	BRS	L6	1670	5 same electrically	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/09 15:23
7	BRS	L7	21	6 same (first near3 pad) same (second near3 pad)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/07/09 15:24